Title (en)

COPPER ALLOY SHEET AND PROCESS FOR PRODUCING SAME

Title (de)

KUPFERLEGIERUNGSFOLIE UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)

FEUILLE D'ALLIAGE DE CUIVRE ET SON PROCÉDÉ DE FABRICATION

Publication

EP 2508635 A4 20151125 (EN)

Application

EP 10834585 A 20101201

Priority

- JP 2009274994 A 20091202
- JP 2010071518 W 20101201

Abstract (en)

[origin: EP2508635A1] {Problems} To provide a copper alloy sheet material, which is excellent in the bending property, and has an excellent mechanical strength, and which is thus suitable for lead frames, connectors, terminal materials, and the like, for electrical/electronic equipments, for connectors, for example, to be mounted on automotive vehicles, and for terminal materials, relays, switches, and the like; and to provide a production method of the same. {Means to solve} A copper alloy sheet material, having an R value of 1 or greater, which is defined by: R = BR + RDW + W / C + S + B wherein [BR], [RDW], [W], [C], [S], and [B] represent an area ratio of crystal texture orientation component of BR orientation {3 6 2} <8 5 3>, RD-rotated-cube orientation {0 1 2} <1 0 0>, cube orientation {1 0 0} <0 0 1>, copper orientation {1 2 1} <1 1 1>, S-orientation {2 3 1} <3 4 6>, and brass orientation {1 1 0} <1 1 2>, respectively, in crystal orientation analysis in an EBSD (electron back scatter diffraction) analysis, and having a proof stress of 500 MPa or greater, and an electrical conductivity of 30%IACS or higher; and a production method of the same.

IPC 8 full level

C22C 9/06 (2006.01); **C22C 9/00** (2006.01); **C22C 9/02** (2006.01); **C22C 9/04** (2006.01); **C22C 9/05** (2006.01); **C22C 9/10** (2006.01); **C22F 1/00** (2006.01); **C22F 1/08** (2006.01); **H01B 1/02** (2006.01); **H01B 5/02** (2006.01)

CPC (source: EP KR US)

C22C 9/00 (2013.01 - KR); **C22C 9/06** (2013.01 - EP KR US); **C22F 1/08** (2013.01 - EP KR US); **H01B 1/02** (2013.01 - KR); **H01B 1/026** (2013.01 - EP US)

Citation (search report)

- [A] EP 1967596 A1 20080910 - DOWA METALTECH CO LTD [JP]
- [AP] US 2009301614 A1 20091210 - ERA NAOHIKO [JP], et al
- See references of WO 2011068135A1

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Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

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DOCDB simple family (application)

EP 10834585 A 20101201; CN 201080051567 A 20101201; JP 2010071518 W 20101201; JP 2011513178 A 20101201; KR 20127012528 A 20101201; US 201213486903 A 20120601